

TDS:EMIC

拓 電 半 導 體

自主封測 品質把控 售後保障

WEB | WWW.TDSEMIC.COM



電源管理



顯示驅動



二三極管



LDO穩壓器



觸摸芯片



MOS管



運算放大器



存儲芯片



MCU



串口通信

PESD3V3S1BA

產品規格說明書

Description

Low capacitance bidirectional ElectroStatic Discharge (ESD) protection diode in a ultra-small and flat lead SOD-523 plastic package designed to protect one signal line from the damage caused by ESD and other transients.

Features

- ★ Ultra Low Capacitance 15 pF(Typ)
- ★ Reverse stand-off voltage: 3.3V Max
- ★ Low leakage current: nA Level
- ★ Response time is typically < 1 ns
- ★ IEC61000-4-2 Level 4 ESD Protection

SOD-523

Applications

- ★ High- speed data lines
- ★ Smart phones
- ★ Display Ports
- ★ MDDI Ports
- ★ USB Ports
- ★ Digital Video Interface (DVI)
- ★ PCI Express and Serial SATA Ports



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
PESD3V3S1BA	SOT-523	3000

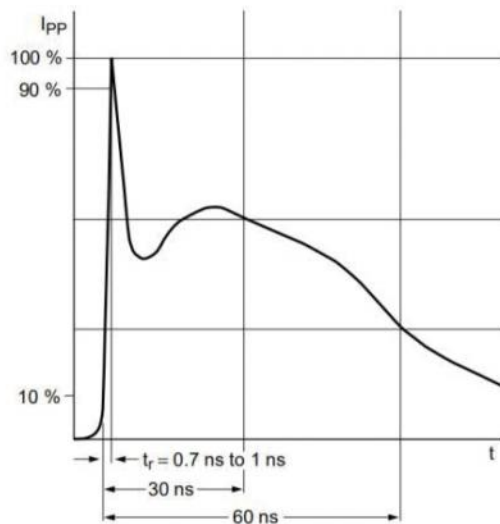
Absolute Ratings(Tamb = 25°C)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp = 8/20μs)	P _{PPM}	100	W
Peak Pulse Current(tp = 8/20μs)	I _{PPM}	9	A
Maximum lead temperature for soldering during 10s	T _L	260	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Operating Temperature Range	T _{OP}	-40 to +125	°C
ESD voltage IEC 61000-4-2 (air discharge)	V _{ESD}	15	kV
ESD voltage IEC 61000-4-2 (contact discharge)	V _{ESD}	8	kV

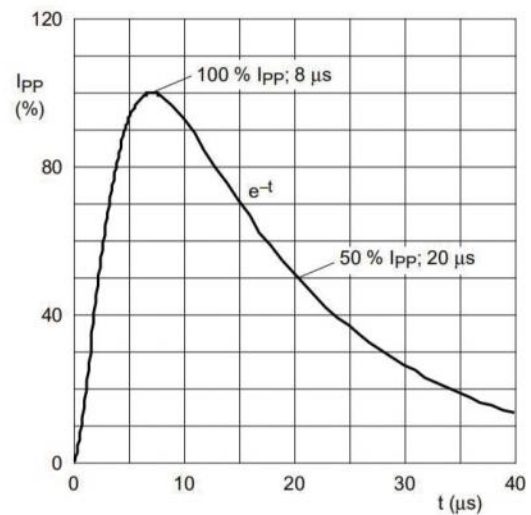
Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	V_{RWM}	--	--	3.3	V	
Breakdown Voltage	V_{BR}	5.6	--	7.8	V	$I_T=1mA$
Leakage Current I_{Leak}	I_R	--	--	1.0	μA	$V_{RWM}=5V$
Clamping Voltage	V_C	--	--	11.0	V	$I_{PP}=4A, T_p=8/20\mu s$
Junction Capacitance	C_J	--	15	--	pF	$V_R=0V, f=1MHz$

Typical Characteristics



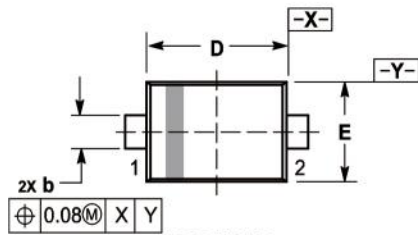
IEC61000-4-2 Waveform



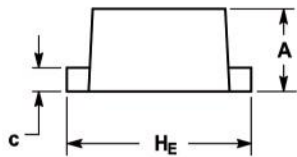
IEC 61000-4-5 Waveform(8/20 μs pulse)

PESD3V3S1BA ESD PROTECTION DIODE

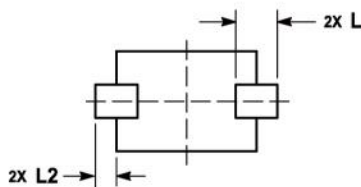
Outline And Dimensions



TOP VIEW



SIDE VIEW



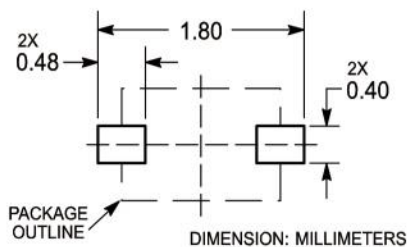
BOTTOM VIEW

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
H _E	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L ₂	0.15	0.20	0.25	0.006	0.008	0.010

Soledering Footprint



DIMENSION: MILLIMETERS